EC4SMA-25.000M

Vibration





Series 4.0mm Epoxy Base SMD Crystal

Frequency Tolerance/Stability ±50ppm at 25°C, ±100ppm over -20°C to +70°C

Mode of Operation AT-Cut Fundamental

-25.000M

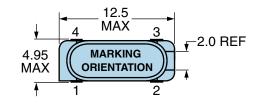
L Nominal Frequency 25.000MHz

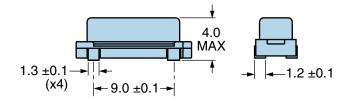
Load Capacitance 18pF Parallel Resonant

ELECTRICAL SPECIFICATIONS			
Nominal Frequency	25.000MHz		
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -20°C to +70°C		
Aging at 25°C	±5ppm/year Maximum		
Load Capacitance	18pF Parallel Resonant		
Shunt Capacitance (C0)	7pF Maximum		
Equivalent Series Resistance	40 Ohms Maximum		
Mode of Operation	AT-Cut Fundamental		
Drive Level	1mWatts Maximum		
Storage Temperature Range	-40°C to +85°C		
Insulation Resistance	500 Megaohms Minimum at 100Vdc		
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS			
Fine Leak Test	MIL-STD-883, Method 1014 Condition A		
Gross Leak Test	MIL-STD-883, Method 1014 Condition C		
Mechanical Shock	MIL-STD-202, Method 213 Condition C		
Resistance to Soldering Heat	MIL-STD-202, Method 210		
Resistance to Solvents	MIL-STD-202, Method 215		
Solderability	MIL-STD-883, Method 2003		
Temperature Cycling	MIL-STD-883, Method 1010		

MECHANICAL DIMENSIONS (all dimensions in millimeters)

MIL-STD-883, Method 2007 Condition A





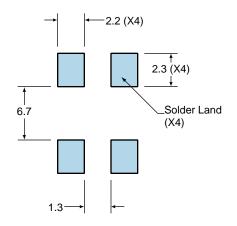
PIN	CONNECTION
1	Connected to Pin 4 and to Crystal
2	Connected to Pin 3 and to Crystal
3	Connected to Pin 2 and to Crystal
4	Connected to Pin 1 and to Crystal
LINE	MARKING
1	E25.000 <i>E=Ecliptek Designator</i>

EC4SMA-25.000M



Suggested Solder Pad Layout

All Dimensions in Millimeters

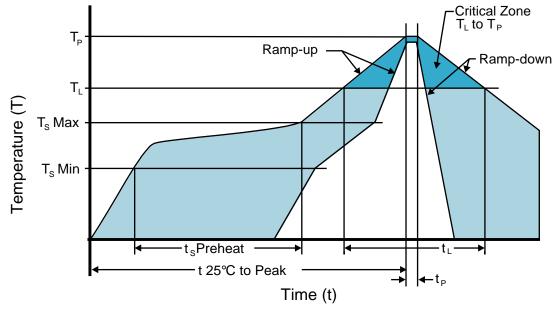


All Tolerances are ±0.1

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 225°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T⊾ to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	225°C Maximum
Target Peak Temperature (T _P Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t _p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.